The resin plating method according to claim 2, wherein the method for reducing the palladium concentration by iodide addition to an etching bath is a method comprising adding to an etching bath at least one iodide selected from the group consisting of sodium iodide, potassium iodide, iodic acid, iodates, periodic acid, and periodates, and separating the formed precipitate.

[Claim 6]

A method for controlling a resin plating etching bath, comprising maintaining the palladium concentration in a manganese-containing acidic etching bath at 100 mg/L or less.